



PART NO. : TG49-1505NXRL

FOUR-PORT T1/E1 ISOLATION MODULE
RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C
UL/EN60950 AND DEMKO RECOGNIZED
EXTENDED OPERATING TEMPERATURE -40/+85°C

ELECTRICAL SPECIFICATIONS @25° C

URNS RATIO

P1-3:P40-39,P6-8:P35-34, 1CT:2 ±2%
P11-13:P30-29,P16-18:P25-24
P4-5:38-36,P9-10:P33-31, 1:2CT ±2%
P14-15:P28-26,P19-20:P23-21

ACL

P1-3,P4-5,P6-8,P9-10, 1.5mH typ
P11-13,P14-15,P16-18,P19-20

DCR

P1-3,P4-5,P6-8,P9-10, 0.8Ω max
P11-13,P14-15,P16-18,P19-20

LL

P1-3,P4-5,P6-8,P9-10, 0.5μH max
P11-13,P14-15,P16-18,P19-20

Cw/w

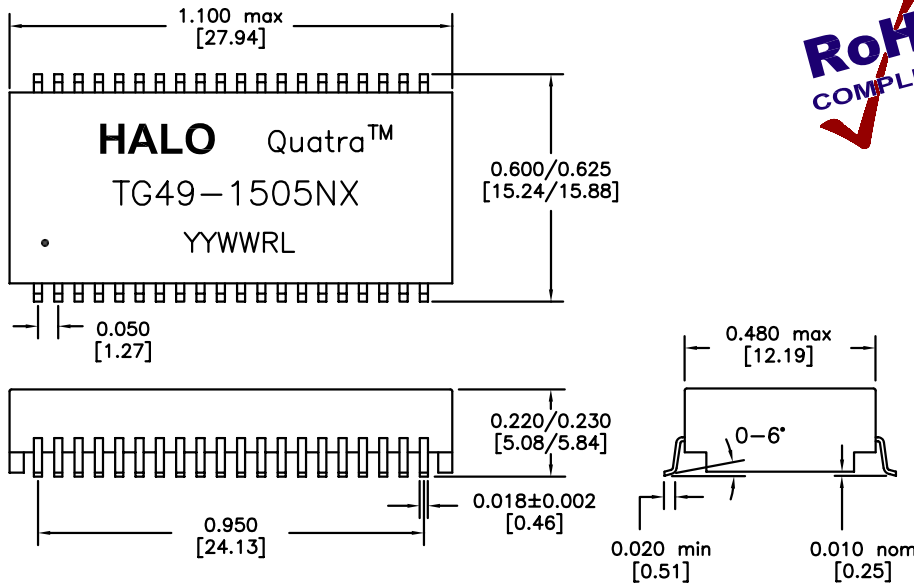
35pF max

CROSSTALK 0.5-5MHz

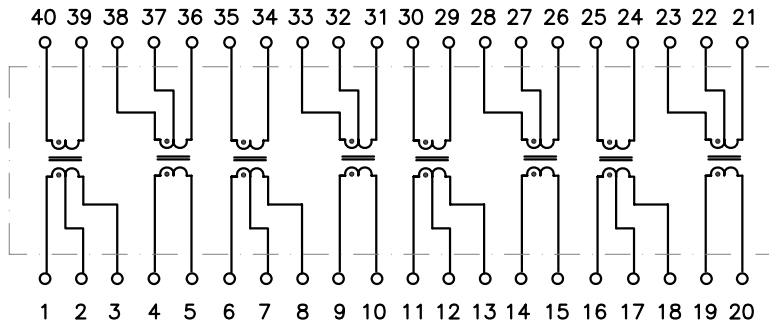
-60dB typ

ISOLATION

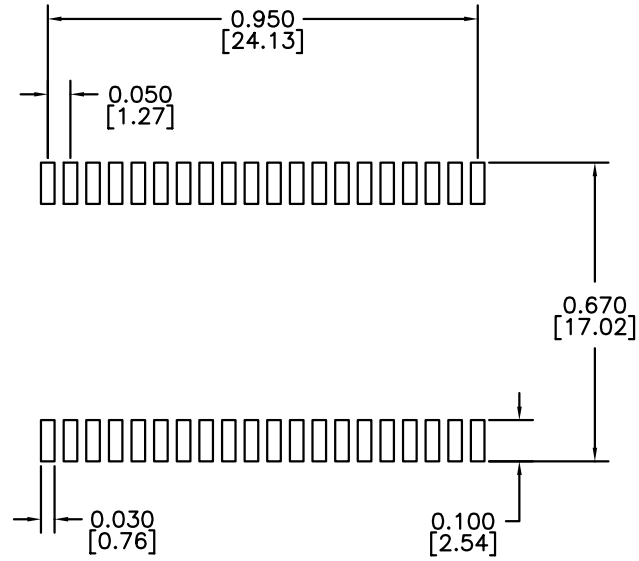
1,500Vrms



DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



HALO/PBL	TITLE	ISOLATION MODULE		SIGNATURES	DATE	REV.	DESC.	DATE
	FOR	T1/E1		DRAWN	LI ZHI ZHONG	11/29/05	A	FIRST ISSUE
	PART NO.	TG49-1505NXRL		CHECKED	LEI KEONG	3/23/11	B	PROD. RELEASE
	SCALE	NONE	PAGE	1 OF 2	APPROVED	PETER LU	3/23/11	
CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE				FILE	TG49NXRL.DWG			



RECOMMENDED SOLDER PAD DIMENSIONS
 DIMENSIONS: Inch [mm]

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	PART NO. TG49-1505NXRL		CHECKED LEI KEONG		3/23/11	B	PROD. RELEASE	3/23/11
	SCALE NONE		PAGE 2 OF 2		APPROVED PETER LU		3/23/11	
CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE		FILE TG49NXRL.DWG						